



SOT2049-1

HX2SON6, thermal enhanced super thin small outline package, no leads, 6 terminals, 0.4 mm pitch, 1.4 mm x 1.2 mm x 0.3 mm body

28 December 2020

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HX2SON6
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
JEDEC package outline code	MO-288
Mounting method type	S (surface mount)
Issue date	27-11-2019
Manufacturer package code	98ASA01549D

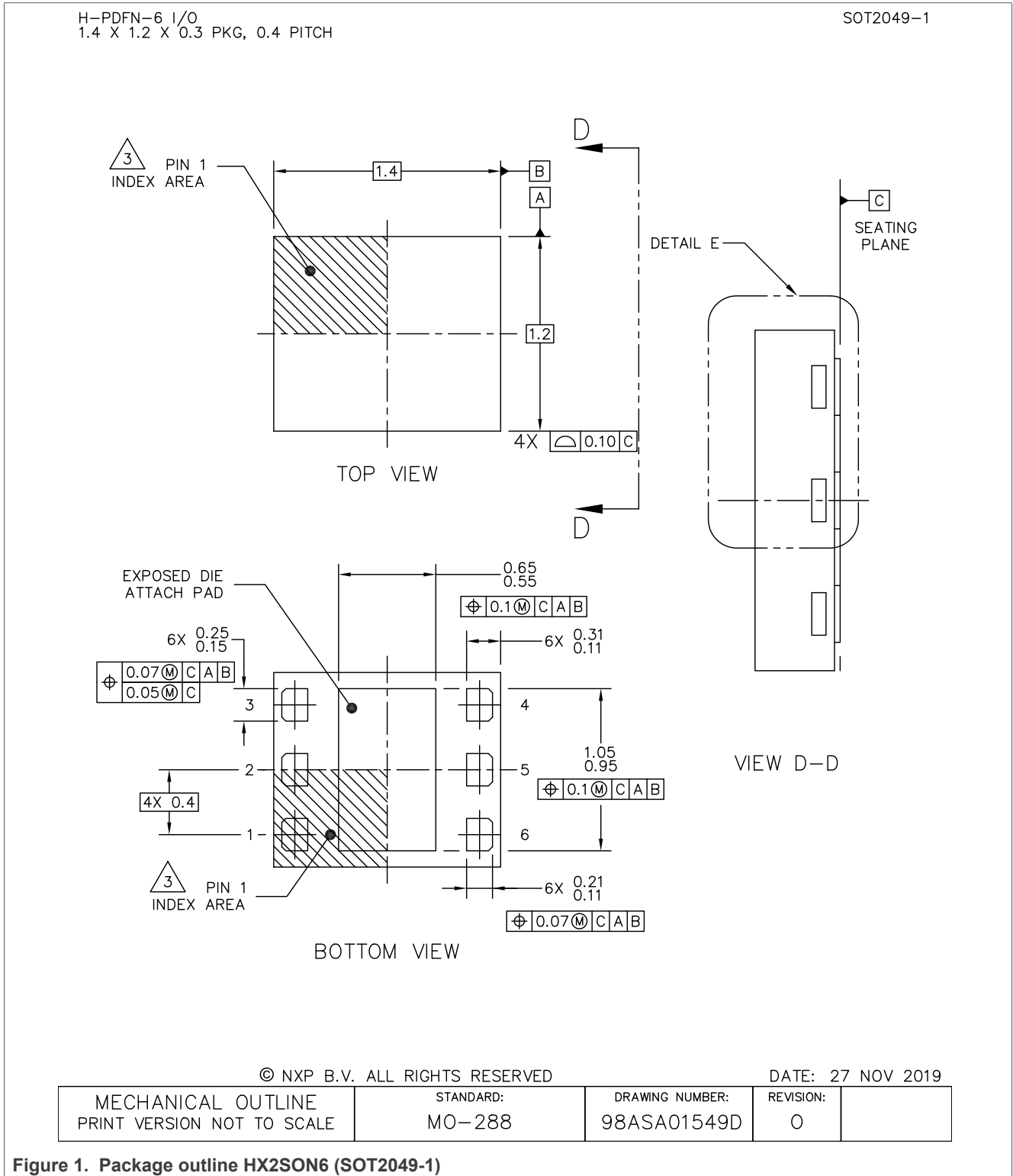
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.3	1.4	1.5	mm
package width	1.1	1.2	1.3	mm
seated height	0.28	0.3	0.32	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	6	-	



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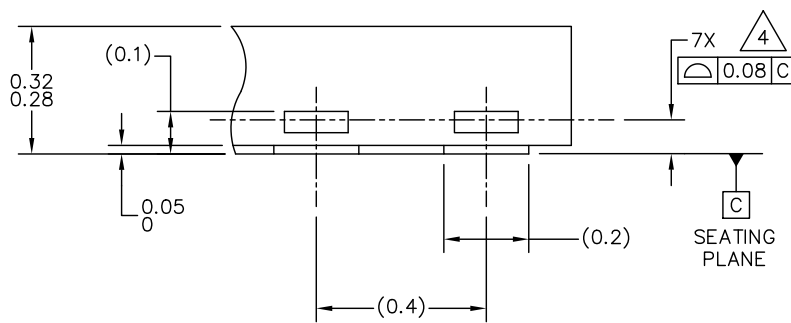
2 Package outline



HX2SON6, thermal enhanced super thin small outline package, no leads, 6 terminals, 0.4 mm pitch, 1.4 mm x 1.2 mm x 0.3 mm body

H-PDFN-6 I/O
1.4 X 1.2 X 0.3 PKG, 0.4 PITCH

SOT2049-1



DETAIL E
VIEW ROTATED 90°CW

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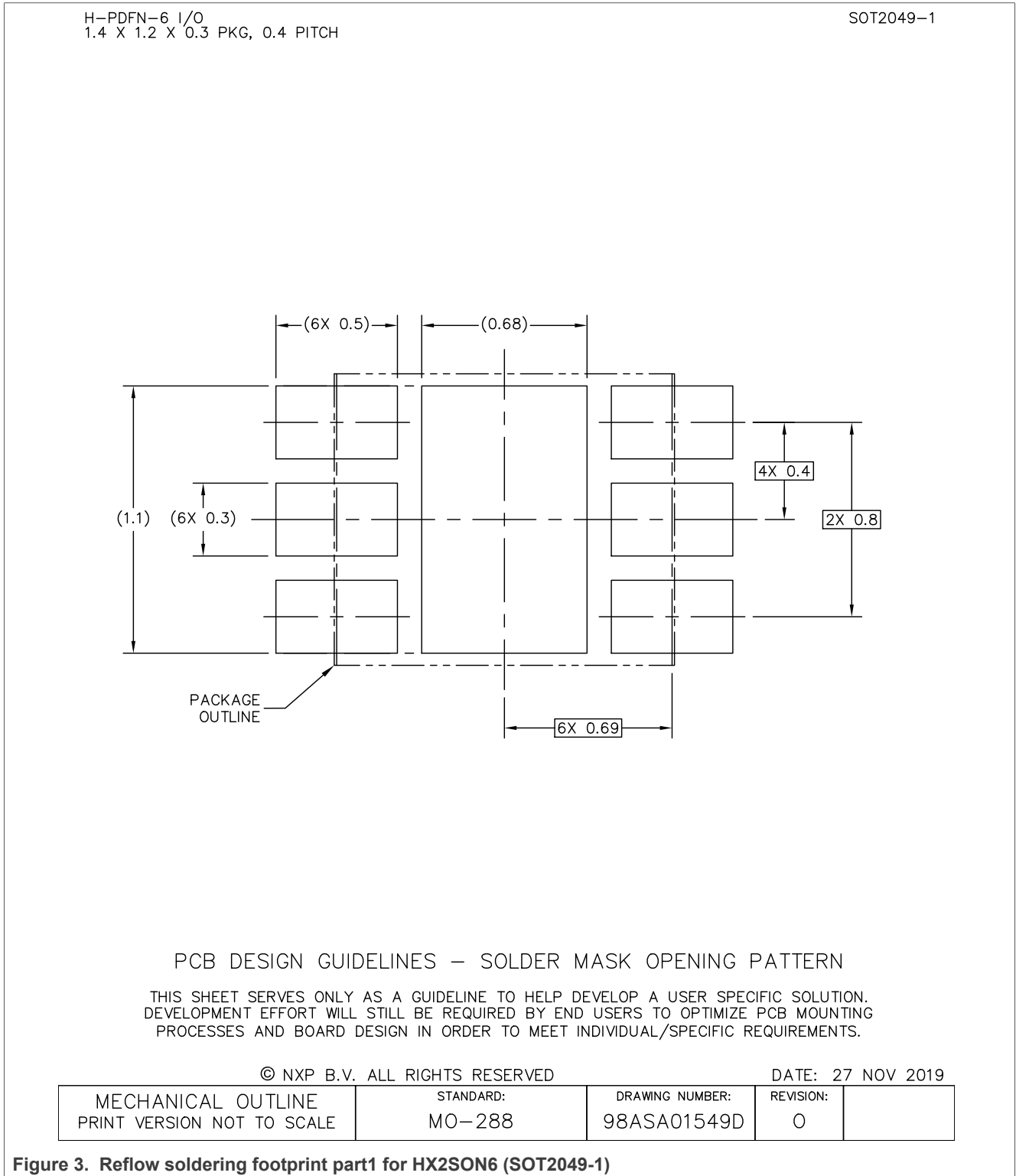
DATE: 27 NOV 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-288	DRAWING NUMBER: 98ASA01549D	REVISION: 0	
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Figure 2. Package outline detail HX2SON6 (SOT2049-1)

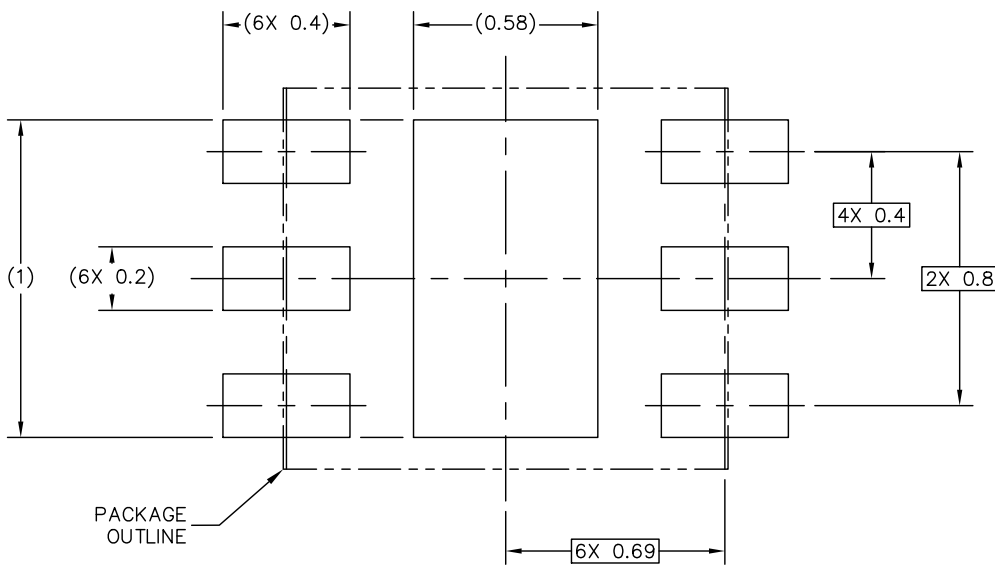
HX2SON6, thermal enhanced super thin small outline package, no leads, 6 terminals, 0.4 mm pitch, 1.4 mm x 1.2 mm x 0.3 mm body

3 Soldering



H-PDFN-6 I/O
1.4 X 1.2 X 0.3 PKG, 0.4 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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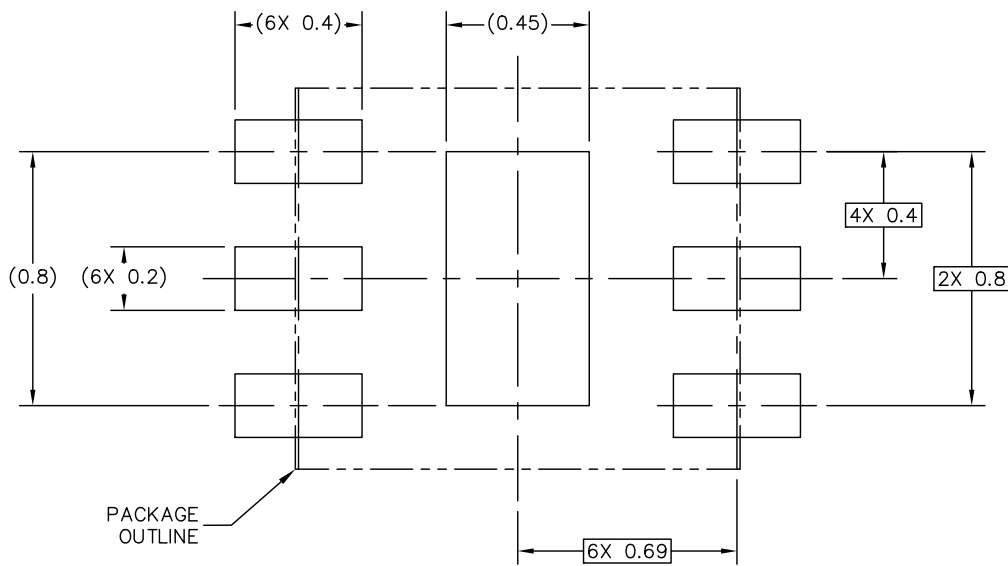
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Figure 4. Reflow soldering footprint part2 for HX2SON6 (SOT2049-1)

HX2SON6, thermal enhanced super thin small outline package, no leads, 6 terminals, 0.4 mm pitch, 1.4 mm x 1.2 mm x 0.3 mm body

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RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HX2SON6 (SOT2049-1)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG PADS.
5. MIN. METAL GAP SHOULD BE 0.15 MM.

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Figure 6. Package outline note HX2SON6 (SOT2049-1)

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4 Legal information

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